

ABSTRACT OF THE DISCLOSURE

A microelectronic assembly includes a microelectronic element having a front face including contacts, a back surface remote from the front face and edges extending therebetween. A mass of a dielectric material at least partially encapsulates the microelectronic element. The microelectronic assembly includes conductive units embedded in the mass of dielectric material at at least one edge of the microelectronic element, whereby at least some of the conductive units are exposed on oppositely-facing exterior surfaces of the mass of dielectric material. Conductive elements extend through the mass of dielectric material and electrically interconnect the contacts with the conductive units.

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